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## III. AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions, and listings, of claims of the application.

1. (Currently amended) A semiconductor comprising:

a contact\_having a portion that extends on two opposing vertical sides of a vertical structure adjacent a first gate electrode, and wherein the contact contacts a diffusion adjacent the first gate electrode and is insulated <u>horizontally</u> from an adjacent second gate electrode and a <u>spacer adjacent the second gate electrode</u> by an insulating layer.

Claims 2-3 (Cancelled).

4. (Currently amended) The semiconductor of claim 1, wherein the contact includes an upper portion that is larger than a lower, contact portion.

Claims 5-20 (Cancelled).

- 21. (Currently amended) The semiconductor of claim 1, wherein the at least one vertical structure is a spacer.
- 22. (Previously amended) The semiconductor of claim 21, wherein the contact contacts a substrate adjacent the spacer.

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Claims 23-33 (Cancelled).

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- 34. (Currently amended) A semiconductor comprising:
  - a gate electrode;
  - a spacer adjacent the gate electrode;
  - a contact having a portion that extends on two opposing vertical sides of a first portion of the spacer, wherein the contact contacts a diffusion adjacent the gate electrode;

an insulating layer having a portion that extends on two opposing vertical sides of a second portion of the spacer and contacts the gate electrode; and

a masking layer contacting the gate electrode for insulating the gate electrode from the contact.

- 35. (Previously added) The semiconductor of claim 34, wherein the masking layer caps at least a portion of the gate electrode.
- 36. (Previously added) The semiconductor of claim 34, wherein the contact has an upper portion that is larger than a lower portion that contacts the diffusion.

Claims 37-42 (Cancelled).

- 43. (Previously added) The semiconductor of claim 35, wherein any remaining portion of the gate electrode is capped by the insulating layer.
- 44. (New) The semiconductor of claim 1, wherein the contact does not horizontally overlap the adjacent second gate electrode.

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45. (New) The semiconductor of claim 34, wherein the contact does not horizontally overlap an adjacent second gate electrode.